



**Advanced Power  
Electronics Corp.**

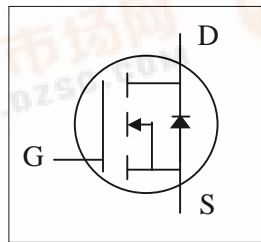
**AP0503GMA**

**Pb Free Plating Product**

*N-CHANNEL ENHANCEMENT MODE*

*POWER MOSFET*

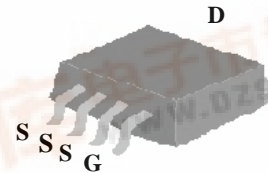
- ▼ SO-8 similar area footprint and pin assignment
- ▼ Low Gate Drive Voltage
- ▼ Lower On-resistance
- ▼ RoHS Compliant



$BV_{DSS}$	30V
$R_{DS(ON)}$	4.2m $\Omega$
$I_D$	75A

## Description

The APAK-5 package is preferred for all commercial-industrial surface mount applications and suited for low voltage applications such as DC/DC converters.



APAK-5

## Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	30	V
$V_{GS}$	Gate-Source Voltage	$\pm 12$	V
$I_D @ T_C = 25^\circ C$	Continuous Drain Current, $V_{GS} @ 4.5V$	75	A
$I_D @ T_C = 100^\circ C$	Continuous Drain Current, $V_{GS} @ 4.5V$	56	A
$I_{DM}$	Pulsed Drain Current <sup>1</sup>	300	A
$P_D @ T_C = 25^\circ C$	Total Power Dissipation	70	W
	Linear Derating Factor	0.6	W/ $^\circ C$
$E_{AS}$	Single Pulse Avalanche Energy <sup>4</sup>	29	mJ
$I_{AR}$	Avalanche Current	24	A
$T_{STG}$	Storage Temperature Range	-55 to 150	$^\circ C$
$T_J$	Operating Junction Temperature Range	-55 to 150	$^\circ C$

## Thermal Data

Symbol	Parameter	Value	Units
Rthj-c	Thermal Resistance Junction-case	Max. 1.8	$^\circ C/W$
Rthj-a	Thermal Resistance Junction-ambient <sup>3</sup>	Max. 85	$^\circ C/W$





# AP0503GMA

## Electrical Characteristics @ $T_j=25^\circ\text{C}$ (unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	30	-	-	V
$\Delta BV_{DSS}/\Delta T_j$	Breakdown Voltage Temperature Coefficient	Reference to $25^\circ\text{C}, I_D=1\text{mA}$	-	0.018	-	$V/^\circ\text{C}$
$R_{DS(ON)}$	Static Drain-Source On-Resistance <sup>2</sup>	$V_{GS}=10V, I_D=30A$	-	-	4.2	$m\Omega$
		$V_{GS}=4.5V, I_D=30A$	-	-	6	$m\Omega$
		$V_{GS}=2.5V, I_D=20A$	-	-	9	$m\Omega$
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}, I_D=250\mu A$	0.5	-	1.2	V
$g_{fs}$	Forward Transconductance	$V_{DS}=5V, I_D=30A$	-	88	-	S
$I_{DSS}$	Drain-Source Leakage Current ( $T_j=25^\circ\text{C}$ )	$V_{DS}=30V, V_{GS}=0V$	-	-	1	$\mu A$
	Drain-Source Leakage Current ( $T_j=150^\circ\text{C}$ )	$V_{DS}=24V, V_{GS}=0V$	-	-	25	$\mu A$
$I_{GSS}$	Gate-Source Leakage	$V_{GS}=\pm 12V$	-	-	$\pm 100$	nA
$Q_g$	Total Gate Charge <sup>2</sup>	$I_D=30A$	-	52	83	nC
$Q_{gs}$	Gate-Source Charge	$V_{DS}=24V$	-	8	-	nC
$Q_{gd}$	Gate-Drain ("Miller") Charge	$V_{GS}=4.5V$	-	21	-	nC
$t_{d(on)}$	Turn-on Delay Time <sup>2</sup>	$V_{DS}=15V$	-	19	-	ns
$t_r$	Rise Time	$I_D=30A$	-	83	-	ns
$t_{d(off)}$	Turn-off Delay Time	$R_G=3.3\Omega, V_{GS}=5V$	-	60	-	ns
$t_f$	Fall Time	$R_D=0.5\Omega$	-	115	-	ns
$C_{iss}$	Input Capacitance	$V_{GS}=0V$	-	5130	8200	pF
$C_{oss}$	Output Capacitance	$V_{DS}=25V$	-	620	-	pF
$C_{riss}$	Reverse Transfer Capacitance	$f=1.0\text{MHz}$	-	360	-	pF
$R_g$	Gate Resistance	$f=1.0\text{MHz}$	-	0.85	1.3	$\Omega$

## Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_{SD}$	Forward On Voltage <sup>2</sup>	$I_S=45A, V_{GS}=0V$	-	-	1.3	V
$t_{rr}$	Reverse Recovery Time <sup>2</sup>	$I_S=30A, V_{GS}=0V,$	-	38	-	ns
$Q_{rr}$	Reverse Recovery Charge	$di/dt=100A/\mu s$	-	30	-	nC

### Notes:

1. Pulse width limited by safe operating area.
2. Pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$ .
3. Surface mounted on FR4 board.
4. Starting  $T_j=25^\circ\text{C}$ ,  $V_{DD}=25V$ ,  $L=0.1\text{mH}$ ,  $R_G=25\Omega$

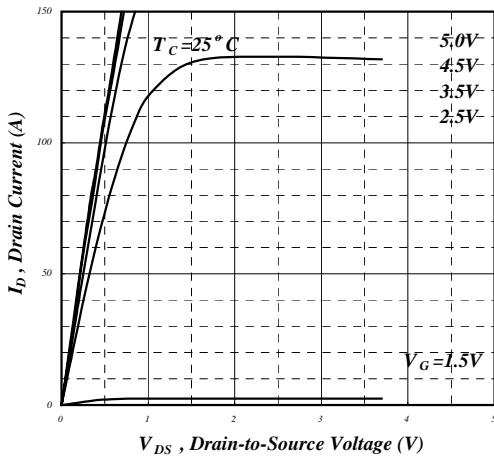


Fig 1. Typical Output Characteristics

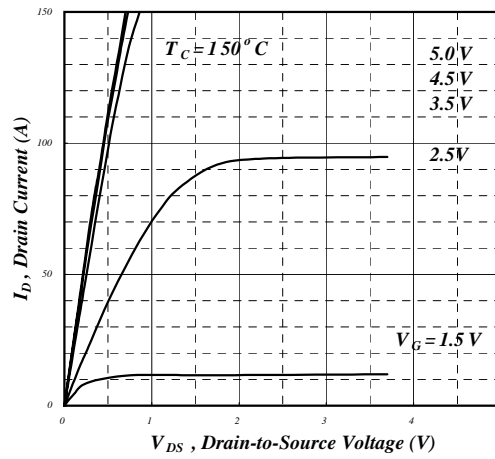


Fig 2. Typical Output Characteristics

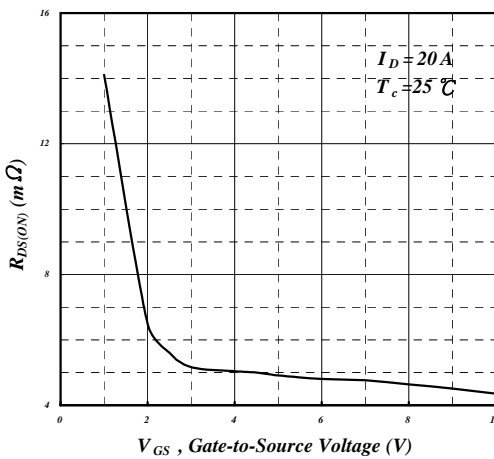


Fig 3. On-Resistance v.s. Gate Voltage

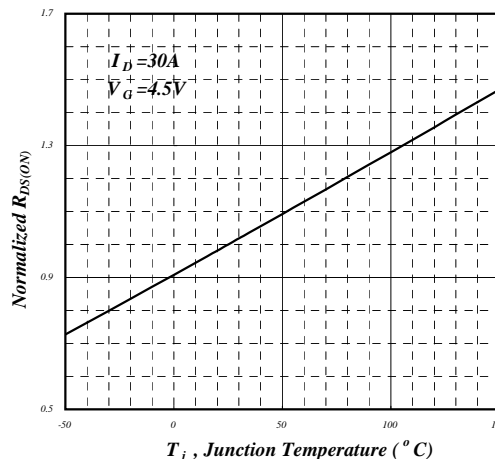


Fig 4. Normalized On-Resistance v.s. Junction Temperature

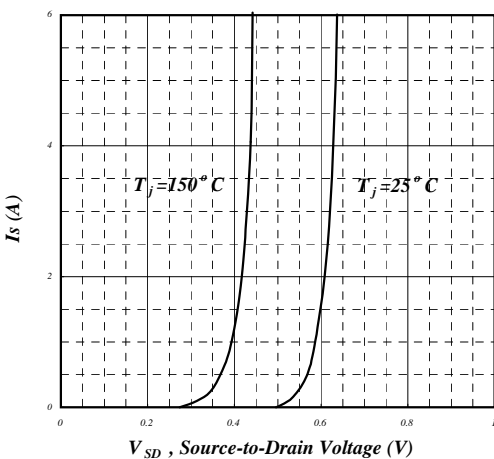


Fig 5. Forward Characteristic of Reverse Diode

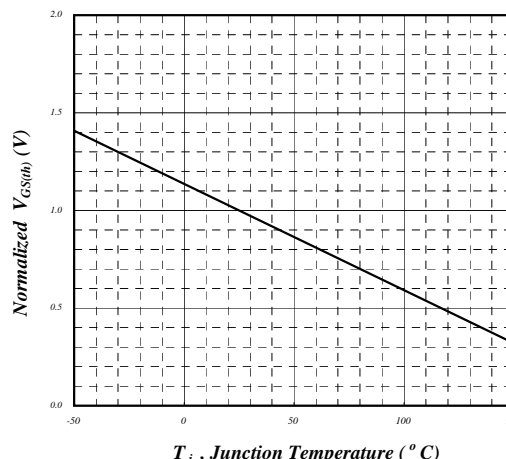


Fig 6. Gate Threshold Voltage v.s. Junction Temperature



# AP0503GMA

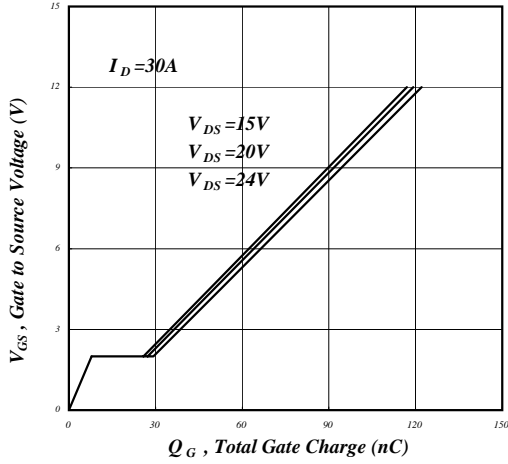


Fig 7. Gate Charge Characteristics

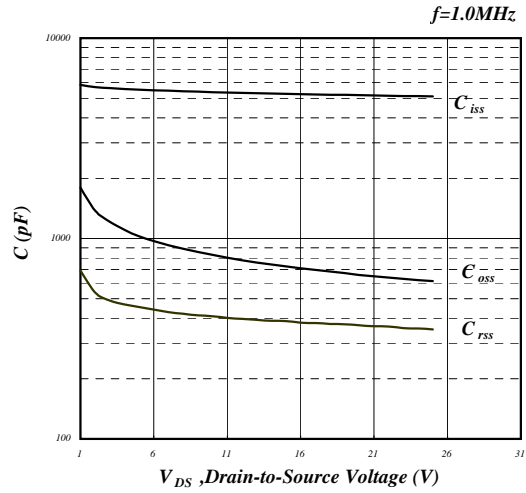


Fig 8. Typical Capacitance Characteristics

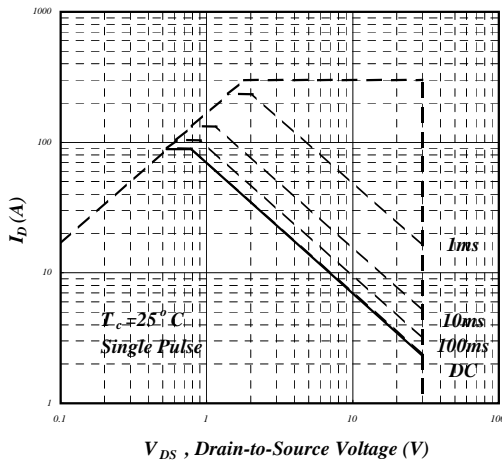


Fig 9. Maximum Safe Operating Area

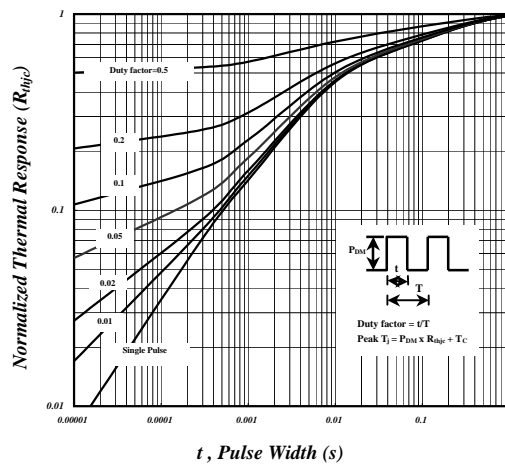


Fig 10. Effective Transient Thermal Impedance

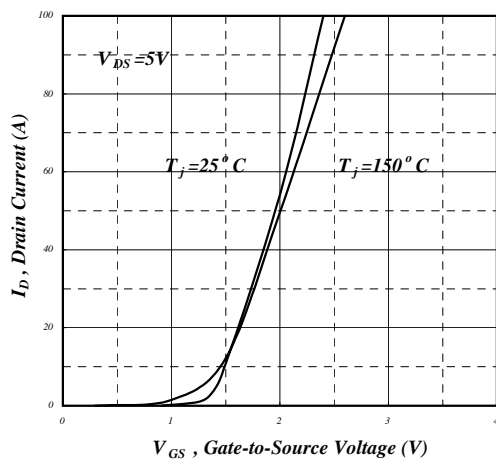


Fig 11. Transfer Characteristics

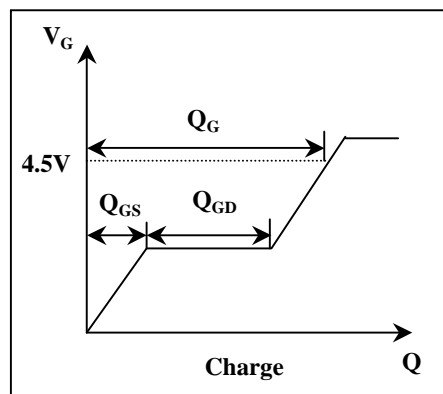


Fig 12. Gate Charge Waveform